



Material Content Data Sheet



Sales Product Name				IPD60R170CFD7		Issued		24. January 2018	
MA#				MA001791312					
Package				PG-TO252-3-313		Weight*		319.78 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.363	1.36	1.36	13644	13644	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138		
	non noble metal	iron	7439-89-6	0.147	0.05		461		
	non noble metal	copper	7440-50-8	147.096	46.01	46.07	459988	460587	
	non noble metal	aluminium	7429-90-5	1.875	0.59	0.59	5862	5862	
wire	non noble metal	aluminium	7429-90-5	1.875	0.59	0.59	5862	5862	
encapsulation	organic material	carbon black	1333-86-4	1.382	0.43		4323		
	plastics	epoxy resin	-	24.191	7.56		75649		
	inorganic material	silicondioxide	60676-86-0	112.663	35.23	43.22	352310	432282	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11696	11696	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4442	4453	
solder	non noble metal	tin	7440-31-5	0.073	0.02		229		
	noble metal	silver	7440-22-4	0.091	0.03		286		
	non noble metal	lead	7439-92-1	3.490	1.09	1.14	10913	11428	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		60		
	non noble metal	copper	7440-50-8	19.177	6.00	6.01	59970	60048	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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